



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/695,018	10/27/2003	Chi-Hsing Hsu	JCLA11476	4247
7590	07/07/2004		EXAMINER	
JC. Patents, Inc. Suite 250 4 Venture Irvine, CA 92618			FARAHANI, DANA	
			ART UNIT	PAPER NUMBER
				2814

DATE MAILED: 07/07/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)	
	10/695,018	HSU ET AL.	
Examiner	Art Unit		
Dana Farahani	2814		

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
 - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
 - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
 - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 27 October 2003.

2a) This action is FINAL. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 1-13 is/are pending in the application.
4a) Of the above claim(s) _____ is/are withdrawn from consideration.
5) Claim(s) _____ is/are allowed.
6) Claim(s) 1-13 is/are rejected.
7) Claim(s) _____ is/are objected to.
8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.

10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) All b) Some * c) None of:
1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) Notice of References Cited (PTO-892)
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date .
4) Interview Summary (PTO-413)
Paper No(s)/Mail Date. ____.
5) Notice of Informal Patent Application (PTO-152)
6) Other: ____.

DETAILED ACTION

Claim Rejections - 35 USC § 103

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

2. Claims 1-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Liu et al., hereinafter Liu (US Patent Application Publication 2004/0032019).

Regarding claims 1, 2, 8, 12, and 13, AAPA discloses in figure 1A a chip package structure comprising: a carrier 110 having a surface, a power pad 116 and a ground pad 114, said surface having a die bonding area at the far left, said power pad and said ground pad being on said surface, said power pad and said ground pad being disposed outside said die bonding area; a die 120 having an active surface and a backside corresponding to said active surface, said backside being attached to said die bonding area on said surface of said carrier, said die having a plurality of die pads 126 on said active surface; and at least a passive component 130 disposed between said power pad and said ground pad, said passive component having at least two electrodes 132a and 132b connected to said power pad and ground pad.

AAPA does not disclose a first conducting wire having two ends connected to one of said plurality of die pads and one of said electrodes respectively.

Liu discloses in figure 4 wires 160 and 170 connecting the die 110 to the power pad 120. Liu also discloses this configuration reduces the wire sweep problem during molding (see page 3, paragraph 28). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to connect one conducting wire connected to one of the plurality of die pads and electrodes of the passive components in order to shorten the wire span of the wire 136 in AAPA and reduce the wire sweep problem during molding.

Regarding claim 3, AAPA discloses a signal pad 118.

Regarding claims 4, 5, and 9, a second conducting wire 138 connected to another one of the plurality of die pads and the signal pad.

Regarding claims 6 and 10, Liu discloses on page 2, paragraph 28 that the pad on the capacitor is gold.

Regarding claim 7 and 11, element 120 in figure 4 of Liu is a capacitor.

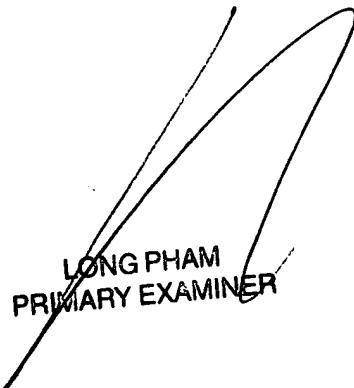
Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dana Farahani whose telephone number is (571)272-1706. The examiner can normally be reached on M-F 9:00AM - 6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael M Fahmy can be reached on (571)272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

D. Farahani



LONG PHAM
PRIMARY EXAMINER

A handwritten signature in black ink, consisting of a stylized, flowing line that loops back on itself. Inside this loop, the name "LONG PHAM" is written in a smaller, more formal, uppercase font. Below "LONG PHAM", the title "PRIMARY EXAMINER" is written in a similar, smaller uppercase font.